



NOTES:

1.MATERIAL:

- 1.1 HOUSING: LCP
- 1.2 CONTACT: BRASS
- 1.3 SHELL: SUS

2.Finish:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: TIN UNDER PLATED SURFACE LAYER

3.SPECIFICATION:

- 3.1 CURRENT RATING: 2.0 A MAX
- 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 V(ac) FOR 1min
- 3.3 CONTACT RESISTANCE: 50 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.
- 3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.
- 3.7 TEMPERATURE RANGE: -30°C ~ +80°C

KSD 科斯达电子科技有限公司
 SWITCH CONNECTOR KSD ELECTRONIC TECHNOLOGY Co., LTD
 全球 互联零组件制造企业

TOLERANCE UNLESS OTHERWISE STATED:	Up to 5 ±0.2	3RD. ANGEL'S	UNITS	MM
	Above 5 ~ 15 ±0.3			
	Above 15 ~ 30 ±0.4			
	Above 30 ~ 50 ±0.5			
	Angle ±0.3°			

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	08/28/17			
CHECKED BY:	DATE	FINISH	MODLE	MICRO USB 5B/F 180度 SMT
Jacky Chen	08/28/17			
APPROVED BY:	DATE	SCALE	DWG NO.	MRUSB-5B-VS4-S316
Tony Kao	08/28/17	1 : 1		
		SHEET NO.	PART NO.	MRUSB-5B-VS4-S316
		1 of 1		

2	更新RATING	Jack	082817
1	新增材質標示	Jack	021417
ITEM NO.	DESCRIPTION	DRAWN	DATE